Dummy Fill Optimization for Enhanced Manufacturability

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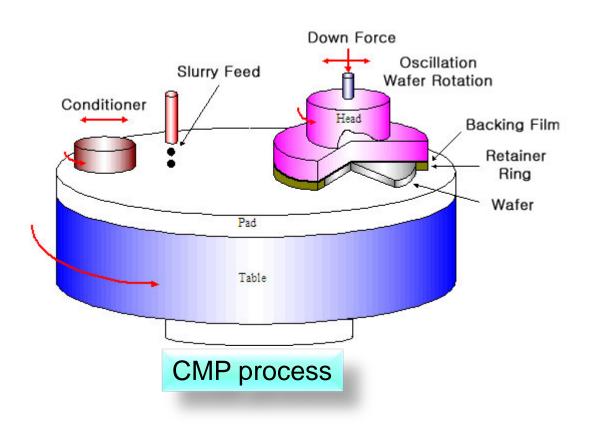
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ISPD 2010

Outline

- Introduction
- Flow of the routing algorithm
- Cost functions
- Experimental results
- Conclusion

Chemical mechanical polishing (CMP)

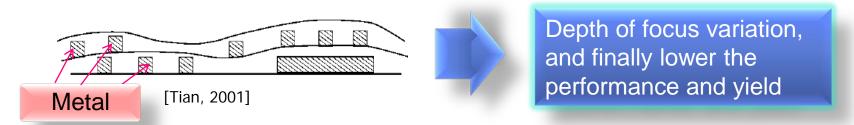
CMP: chemical and mechanical means to polish wafer





Variations caused by oxide CMP

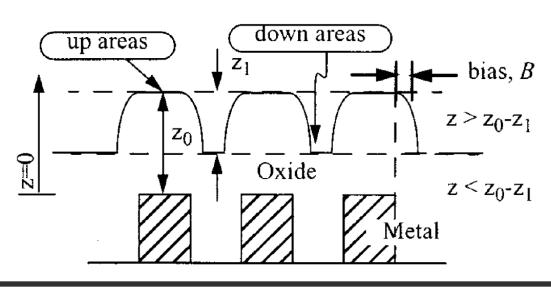
- Oxide CMP used to polish the interlayer dielectric (ILD)
- Variation in the post-CMP ILD thickness



e.g., CMP variation can lead to 30% delay variation [Mehrotra, 2000]

- Oxide CMP model in [Ouma, 2002]
 - Post-CMP ILD
 thickness z ~ effective
 pattern density ρ

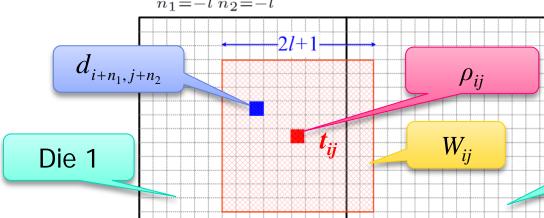
$$z = c_0 + z_1 \rho$$



Effective pattern density (EPD)

- Partition the layout to tiles
- For each tile t_{ii}
 - Initial pattern density (IPD) d_{ij} : Density of metal in a tile
 - Assume the die is periodically repeated, and then d_{ii} is periodic.
 - Effective pattern density (EPD) ρ_{ij} : Weighted sum of d_{ij} over a weighting window W_{ij} with size 2l+1

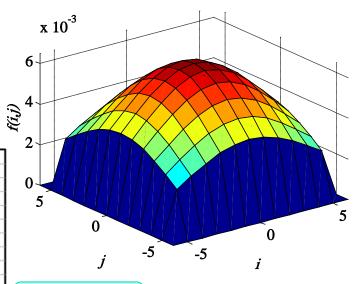
$$\rho_{ij} = \sum_{n_1 = -l}^{l} \sum_{n_2 = -l}^{l} d_{i+n_1, j+n_2} \times f(n_1, n_2)$$



Discretized Gaussian function

$$f(i,j) = \frac{1}{2\pi l^2} \exp(-\frac{i^2 + j^2}{2l^2})$$

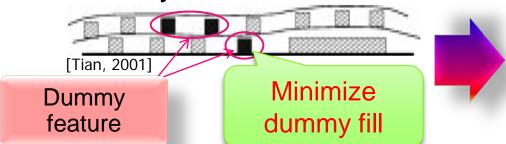
Weighting function with l=5



Die 2

Reduce CMP variation

Add dummy fill



Reduce EPD variation, and ILD thickness variation

Increase routing cost or coupling capacitance

e.g., floating dummy fill may increase the coupling capacitance up to 90% [Kahng, 2006]

- Dummy filling problem formulation
 - Insert minimal amount of dummy fill (D) to make

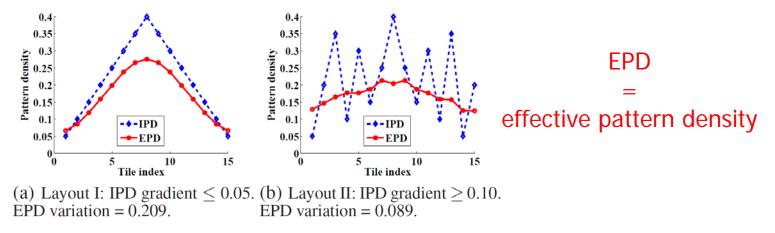
$$ran(\rho) = \rho_H - \rho_L \le \epsilon$$

 $ran(\rho) = \rho_H - \rho_L \le \epsilon$ $(\rho = EPD = effective pattern density)$

- D is a good metric
- Use dummy filling algorithm in [Tian, 2001]
- CMP-aware routing
 - Generate more uniform distribution of wires
 - Reduce variation and D

Previous work and our contributions

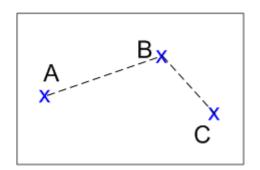
- Previous work of CMP-aware routing
 - No CMP model used
 - Control the maximal initial pattern density [Li, 2005]
 - The metrics used have limitations
 - Minimize the gradient of initial pattern density (IPD) [Chen, 2009]



- Impact of routing on the neighboring regions not considered [Yao, 2007][Jia, 2008]
- Our contributions
 - Use accurate CMP model and metric D (D = amount of required dummy fill)
 - Optimize dummy fill directly

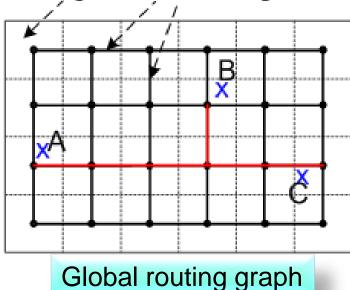
Global routing model

- Input
 - Information for nets/interconnects
- Output
 - Paths on the global routing graph



 Objective: minimize overflow, wire length and amount of dummy fill D

Global grid Global edges

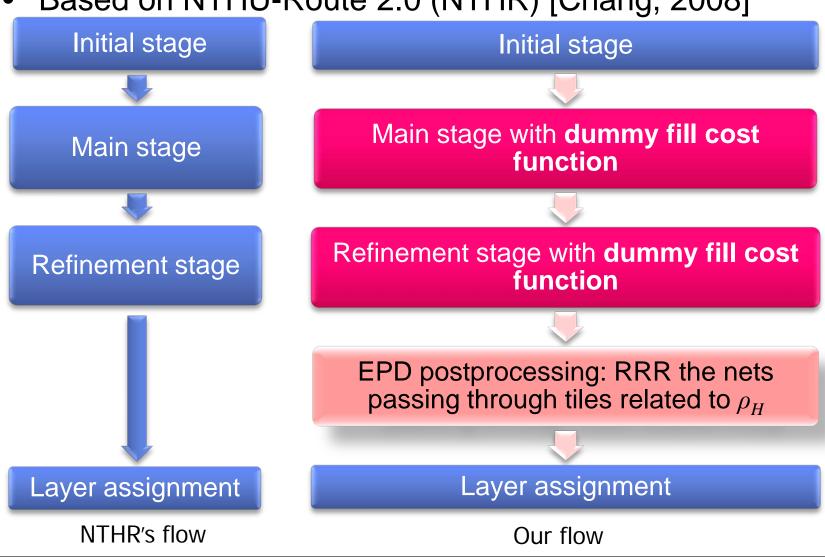


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Algorithm flow

Based on NTHU-Route 2.0 (NTHR) [Chang, 2008]

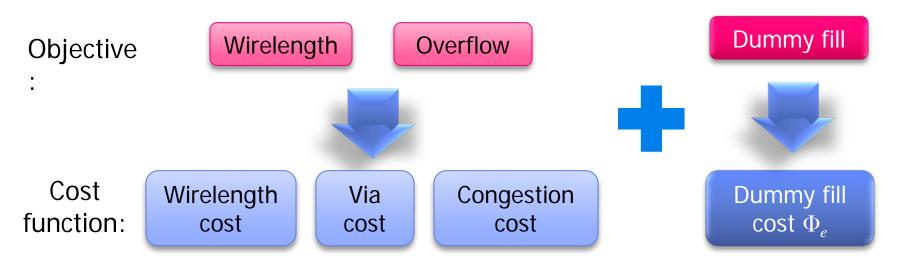


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Big picture of cost function

Achievement of objectives dependent on cost functions



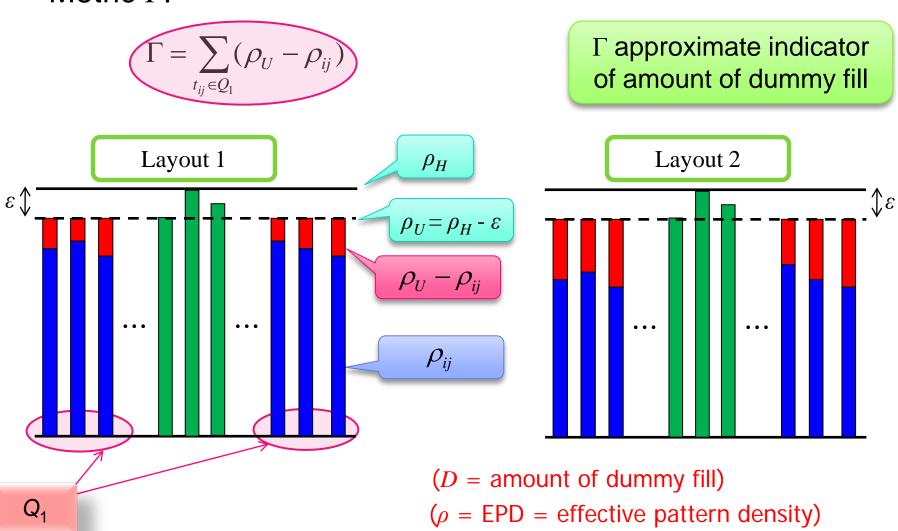
- Dummy fill cost Φ_e
 - Efficient
 - Effective
- Metric: D

(D = amount of dummy fill)

- Linear programming used
- Several minutes required to compute D

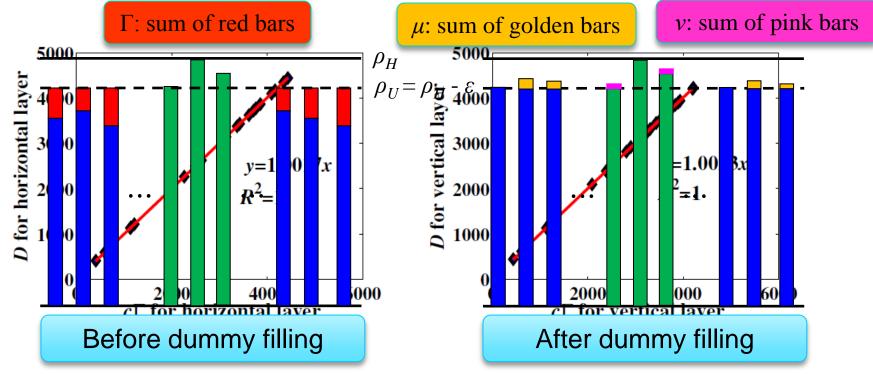
Metric Γ : A surrogate for D

• Metric Γ:



Metric Γ : A surrogate for D

• Theorem 1: $D = c (\Gamma + \mu + \nu)$, where c is constant

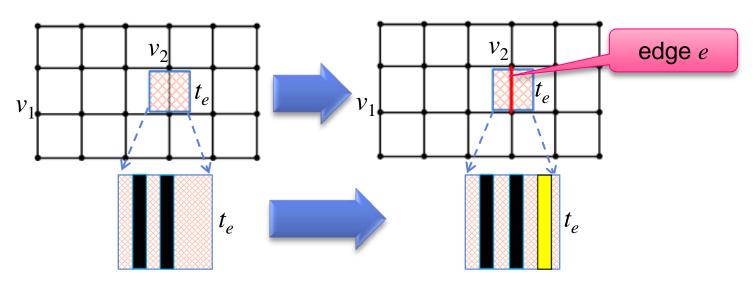


- $\mu+\nu$ much smaller than Γ
 - e.g., for circuit newblue2, $(\mu + \nu)$: $\Gamma = 1$: 483
- Important conclusion: $D \approx c\Gamma$ (D = amount of dummy fill)

A surrogate for Γ

- Γ still too complex to be used
- The impact of routing on Γ and D
- Theorem 2:

(D = amount of dummy fill)



$$\Delta\Gamma \ge |Q_1| \Delta\rho_H - c_1$$

$$(c_1 = a constant)$$

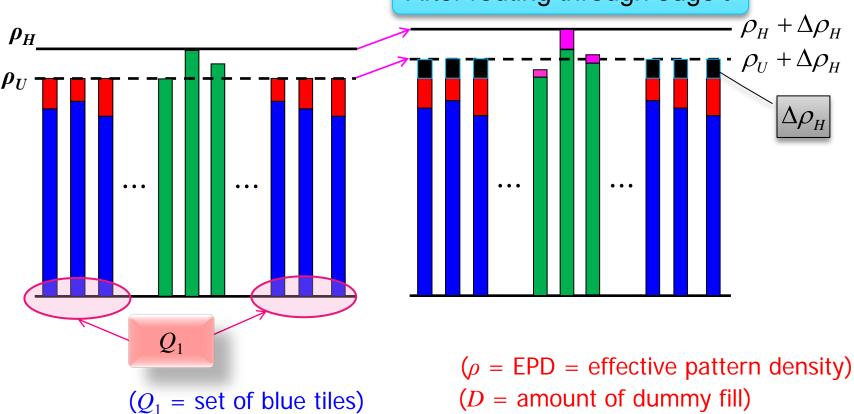
 $(\rho_H = \text{maximal effective pattern density})$

 $(Q_1 = \text{set of blue tiles})$

A surrogate for Γ

• $\Delta\Gamma \geq |Q_1| \Delta\rho_H - c_1$

After routing through edge *e*



- $|Q_1|$ is about 85% of the total number of tiles
- D highly sensitive to the change in ho_H ($Dpprox c\Gamma$)
- Minimizing ρ_H is a good surrogate for minimizing D

Cost function

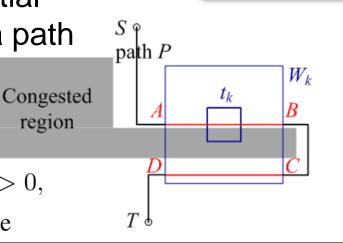
- Compute dummy fill cost Φ_{ρ}
 - Purpose: constrain the increase of ρ_H
- Cost component 0: penalty for direct increase of ρ_H after routing through edge e

$$\Omega_e = \begin{cases} \exp\left(\frac{\Delta\rho_H}{\Delta_\rho^M}\right) & \text{if } \Delta\rho_H > 0, \\ 0 & \text{otherwise} \end{cases}$$

Cost component 1: penalty for potential increase of ρ_H after routing through a path

$$\Delta \rho_H' = \max_{t_k \in W_e} \left(\rho_k + J_M - \rho_H \right)$$

$$\Theta_e = \begin{cases} \exp\left(\frac{\Delta\rho_k}{\Delta_\rho^M}\right) \cdot \exp\left(p_0 \cdot \frac{\Delta\rho_H'}{\Delta_\rho^M}\right) & \text{if } \Delta\rho_H' > 0, \\ 0 & \text{otherwise} \end{cases}$$



region

Tile t_k

Edge e

Weighting

window W_{ρ}

Cost function

 Cost component 2: penalty for routing through the edges in the tiles with large EPD

$$\Psi_e = \frac{p_1}{1 + e^{p_2(1 - \rho_e/\rho_H)}}$$
 Small cost not to affect other objectives too much
$$0 = \frac{p_1}{1 + e^{p_2(1 - \rho_e/\rho_H)}}$$

- Total dummy fill cost: $\Phi_e = \Psi_e + \Theta_e$
- Integrate dummy fill cost function into the original router

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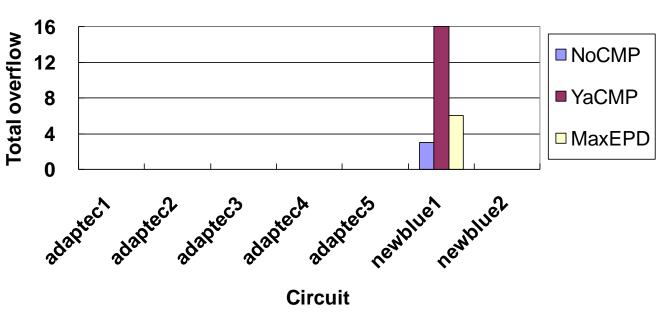
Experimental setup

- Platform
 - A 64-bit Linux machine with an Intel Core(TM)2 Duo 3.00GHz CPU and 8GB memory
- Major assumptions
 - 0.13um technology
 - Size of weighting window 1mm
 - The space between the dies on the wafer is negligible
- ISPD 2007 benchmark
- Comparison
 - NoCMP: the original NTHU router
 - MaxEPD: our algorithm
 - YaCMP: replacing the cost function we propose in MaxEPD by the cost function in [Yao, 2007] (our implementation)
- Parameters tuned using newblue2

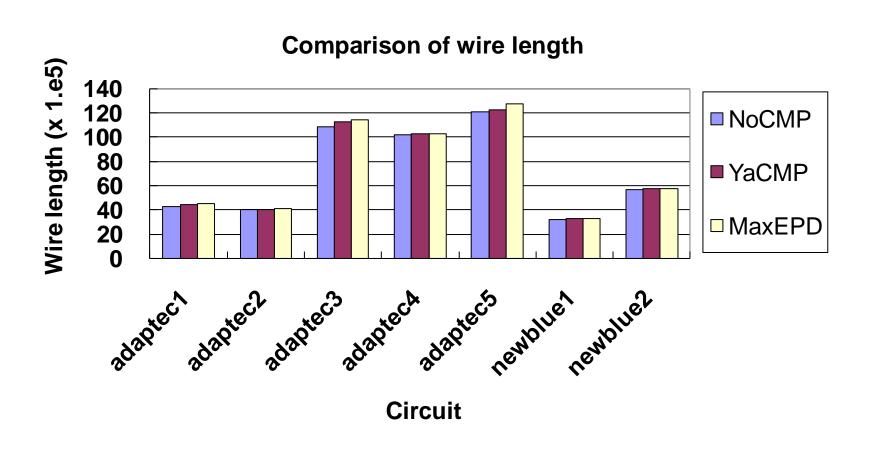
Overflow

- Circuit newblue1 is difficult
- Maximal overflow is 1
- The overflows can be eliminated in later stage with the reserved capacity





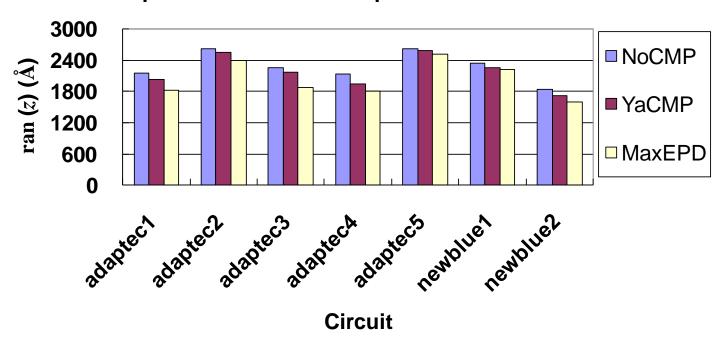
Wire lengths are similar



Variation in the post-CMP ILD thickness

$$ran(z) = z_1 \cdot ran(\rho)$$
 with $z_1 = 7000$ Å

Comparison of variation in post-CMP ILD thickness

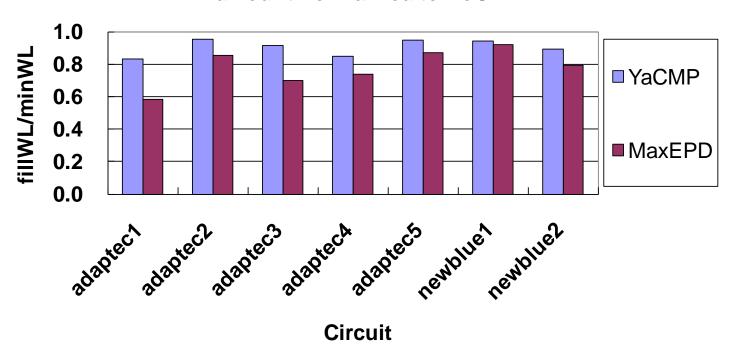


Compared to NoCMP, reduced by 16.7% (max) and 11.1% (average); Compared to YaCMP, reduced by 13.5% (max) and 7.0% (average).

Dummy fill results

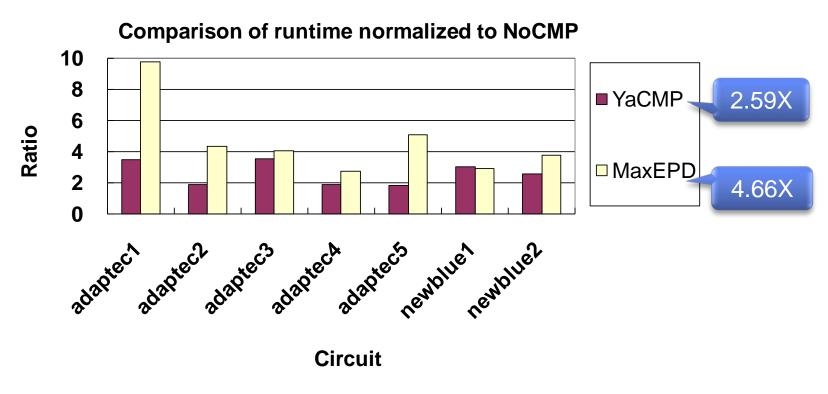
- Amount of dummy fill D
 - Computed using dummy filling algorithm in [Tian, 2001]

Fill amount normalized to NoCMP



Compared to NoCMP, reduced by 41.5% (max) and 22.0% (average); Compared to YaCMP, reduced by 23.6% (max) and 14.1% (average).

Runtime



- Runtime in absolute terms for MaxEPD
 - Less than 1 hour
 - Reasonable

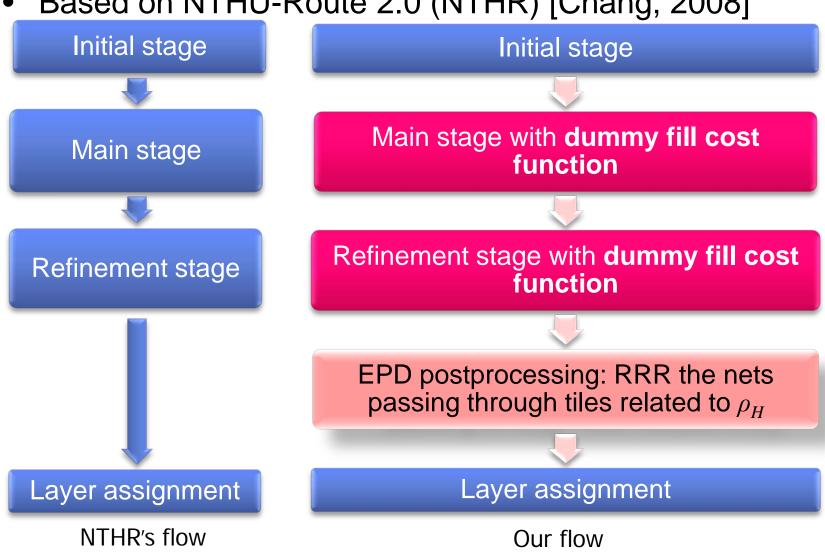
Conclusion

- Develop a global routing algorithm optimizing the amount of dummy fill.
- Minimizing maximal effective pattern density is a good surrogate for minimizing the amount of dummy fill.
- Propose effective cost functions to perform dummy fill optimization.
- Experimental results show that our algorithm can reduce the amount of dummy fill up to 41.5% with ~4x runtime overhead, compared with original router.

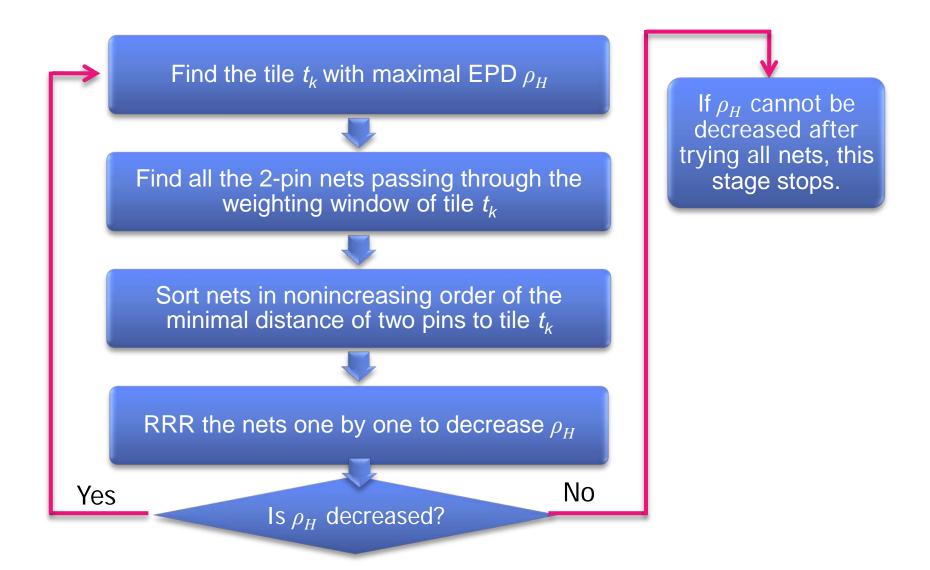
Thank You! Any questions?

Algorithm flow

Based on NTHU-Route 2.0 (NTHR) [Chang, 2008]



EPD postprocessing stage



Why not care about ρ_L

- The change in D after routing through edge e
- $\Delta \rho_H > 0$, we will not use this edge
- $\Delta \rho_H = 0$, maximal ΔD is -1 wire track
 - Many choice of edges
 - No matter how ρ_L changes
 - No need to make efforts to increase ρ_L
- Similar argument for routing through a path